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(12) **United States Design Patent**
Hosaka

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(54) **PAIR OF STAGE ARMS FOR A SEMICONDUCTOR WAFER DELIVERY APPARATUS**

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(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/242,545**

(22) Filed: **Nov. 14, 2005**

(30) **Foreign Application Priority Data**

Aug. 12, 2005 (JP) 2005-023559

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
134/110; 396/611; 414/331.15, 411, 416.03;
700/213

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a pair of stage arms for a semiconductor wafer delivery apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a pair of stage arms for a semiconductor wafer delivery apparatus showing our new design;

FIG. 2 is a front elevation view thereof;

FIG. 3 is a bottom plan view thereof;

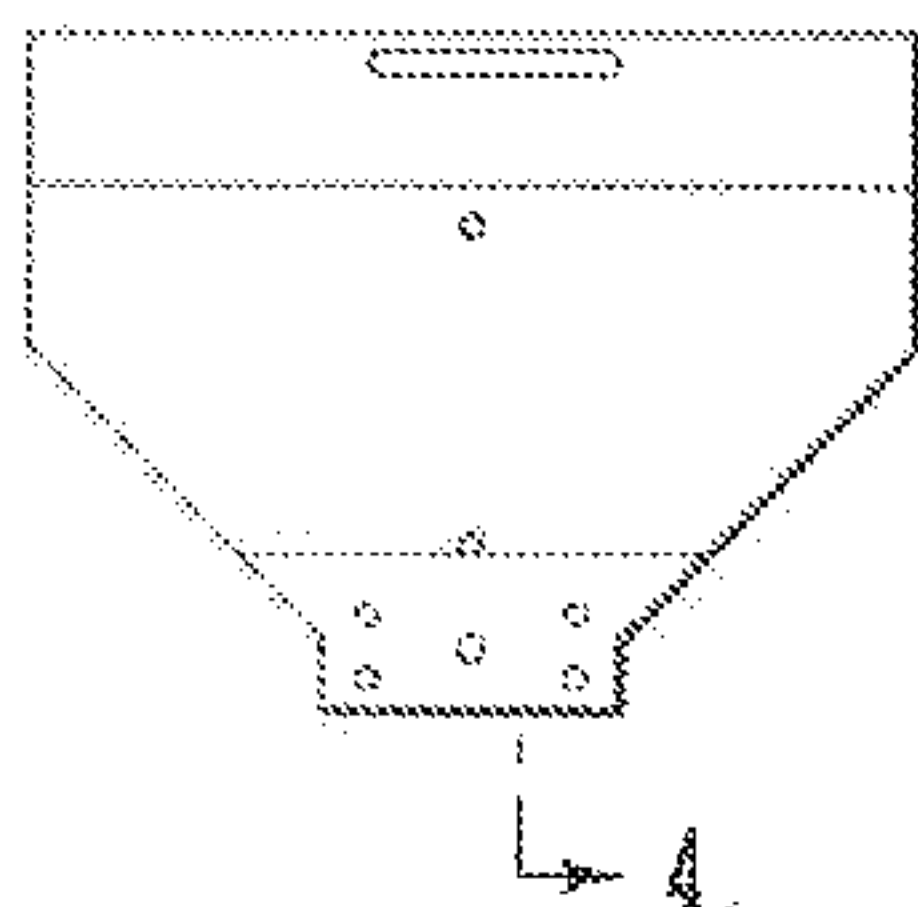
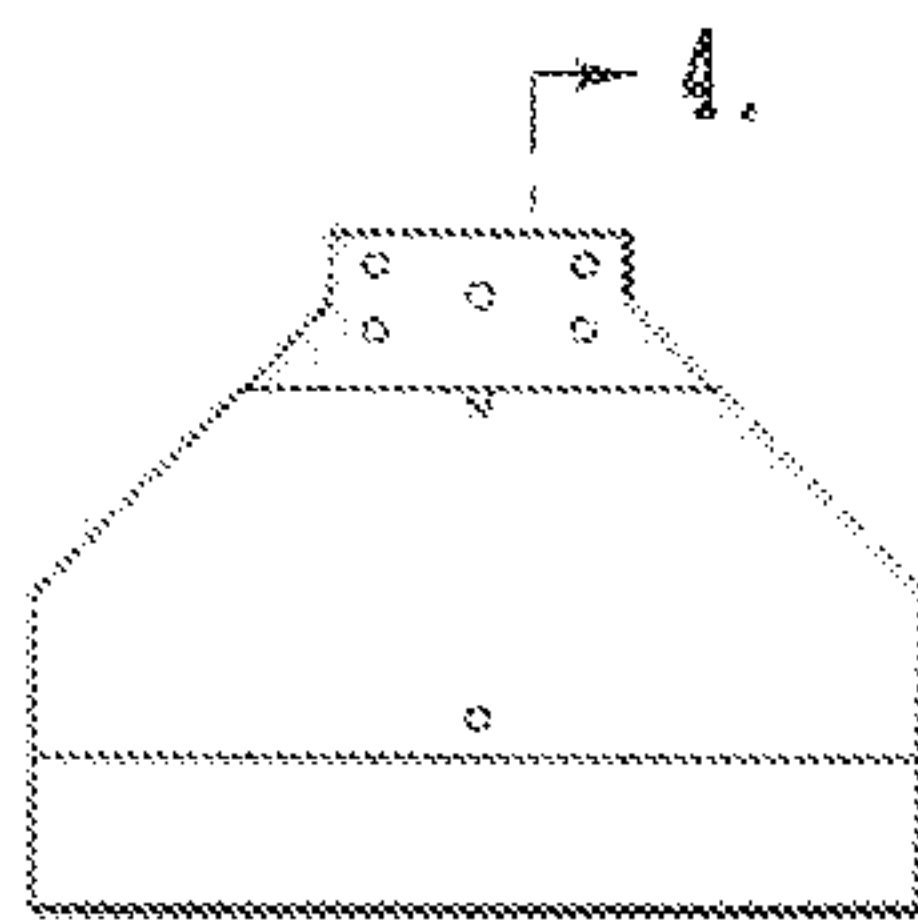
FIG. 4 is a cross-sectional view thereof taken along line 4—4 in FIG. 1;

FIG. 5 is a cross-sectional view thereof taken along line 5—5 in FIG. 4; and,

FIG. 6 is a perspective view thereof in use.

The broken line showing represents unclaimed subject matter.

1 Claim, 4 Drawing Sheets



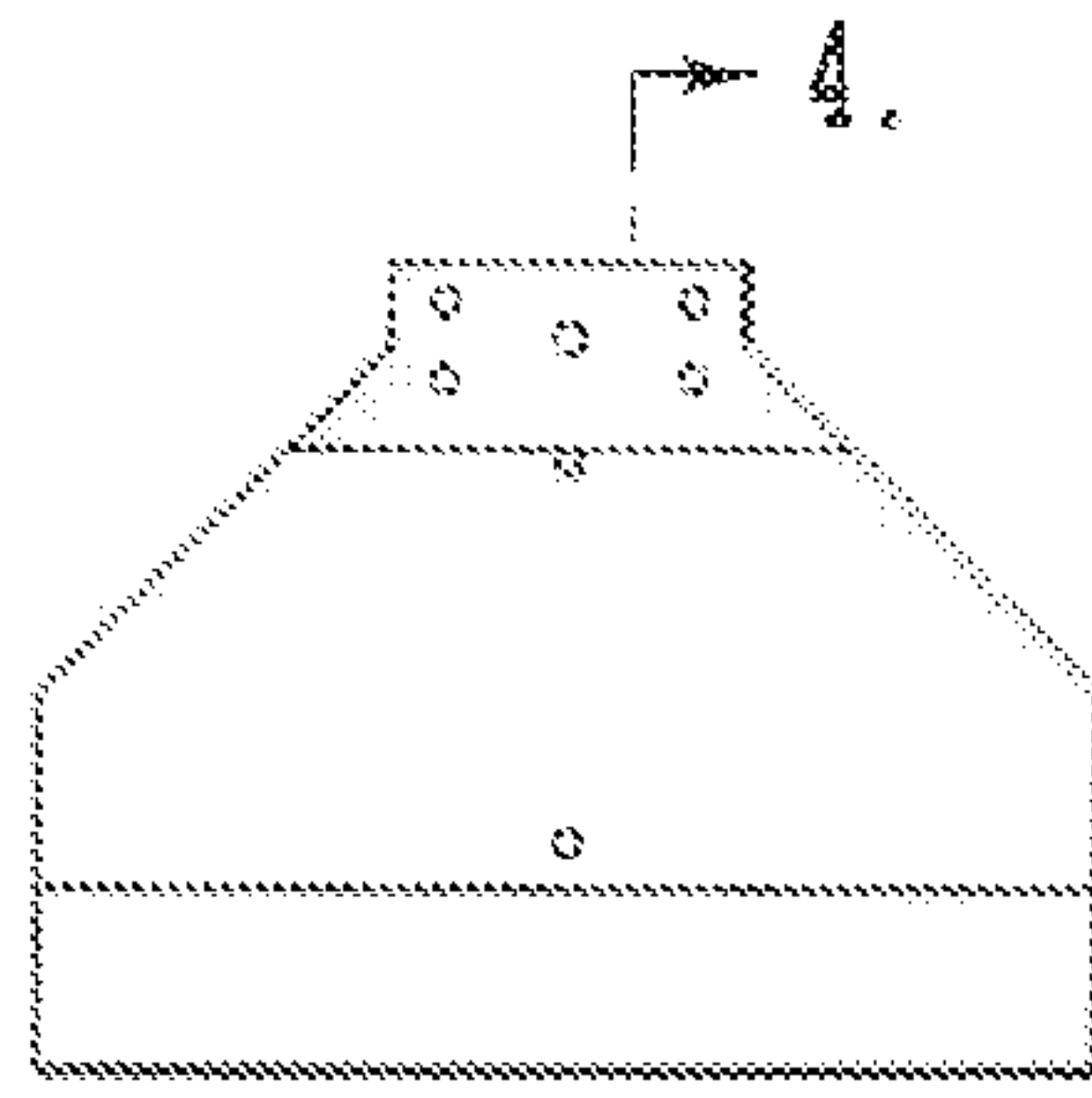


Fig. 1

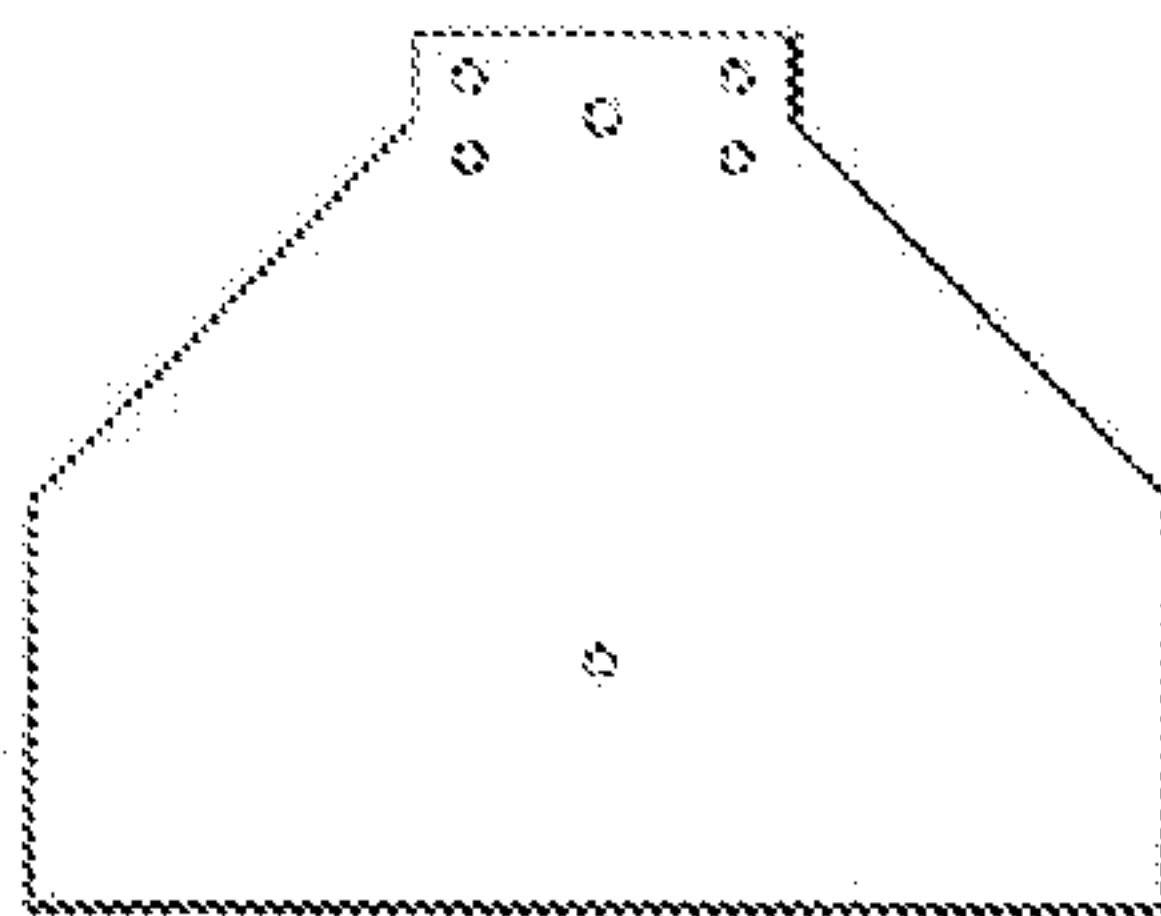
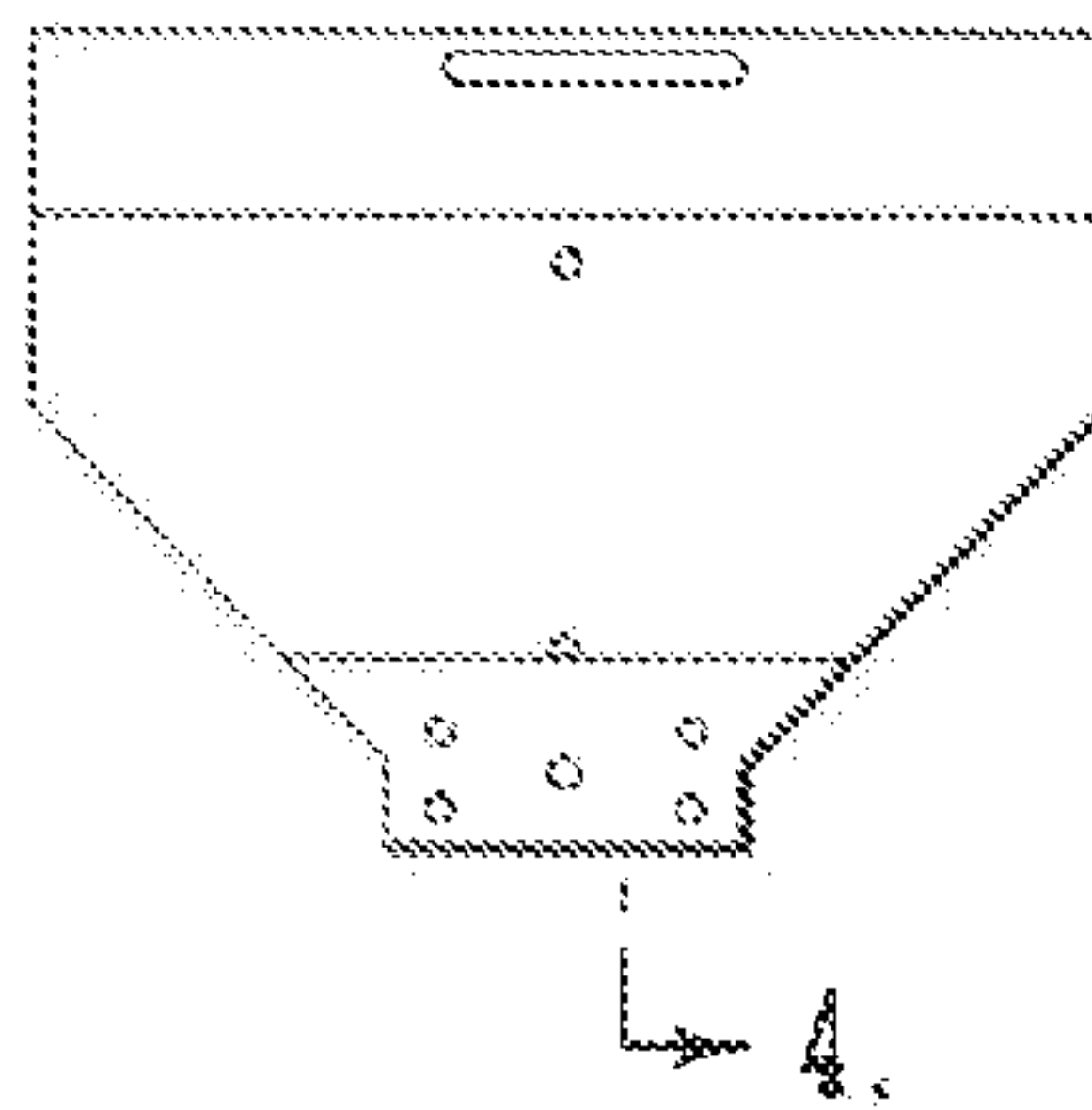
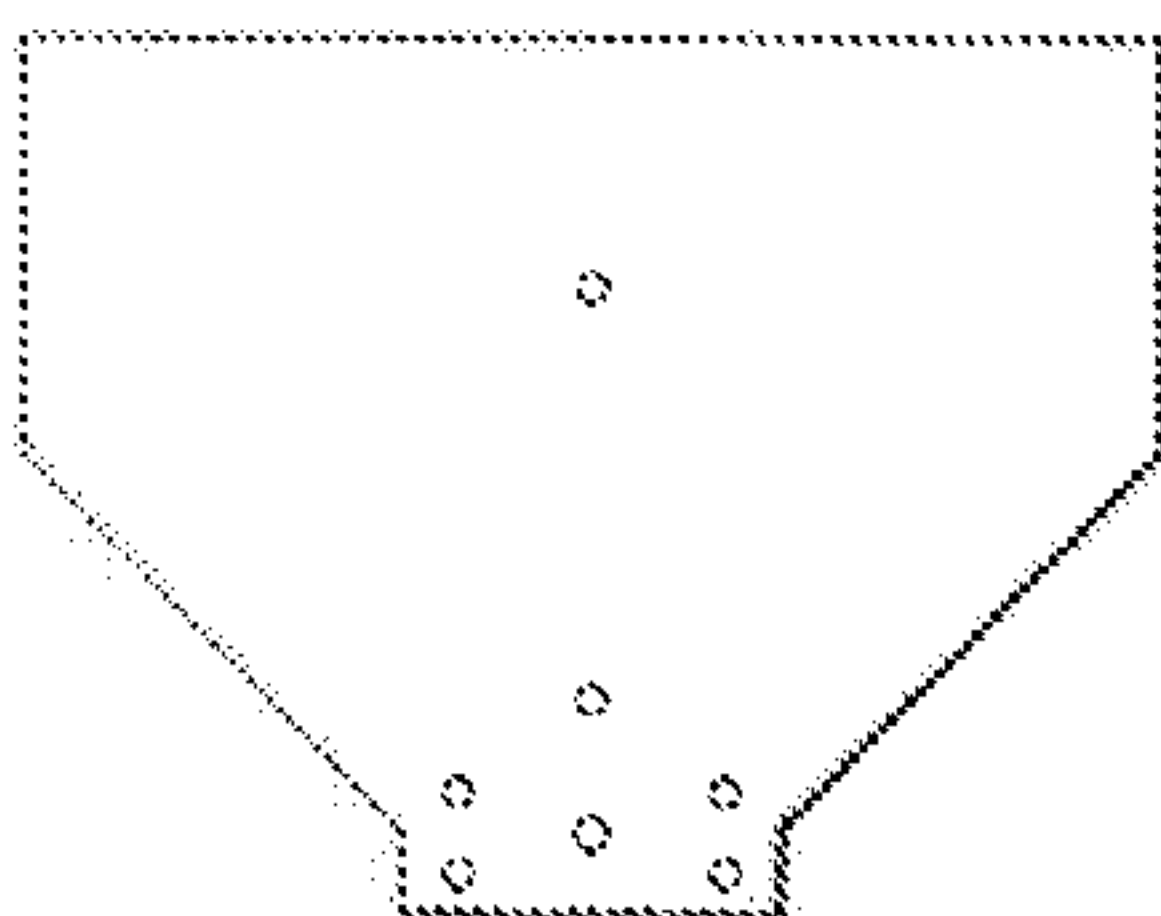


Fig. 2



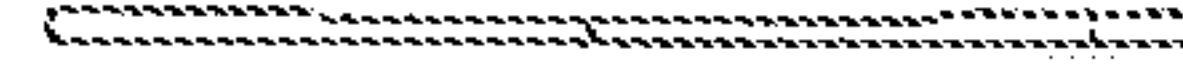
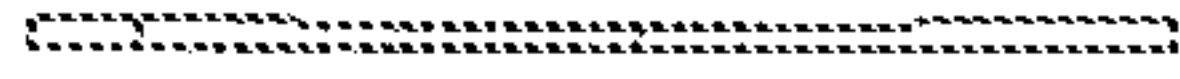


Fig. 3

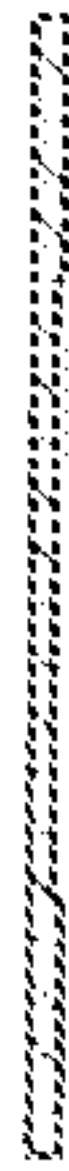
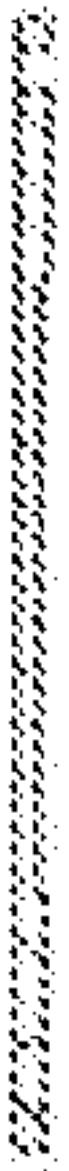


Fig. 4

5.4

5.5



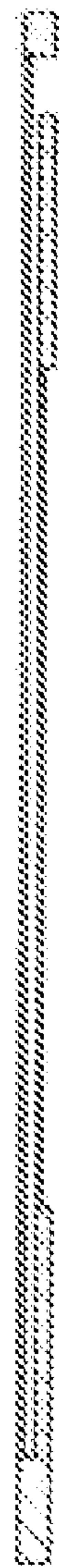


Fig. 5

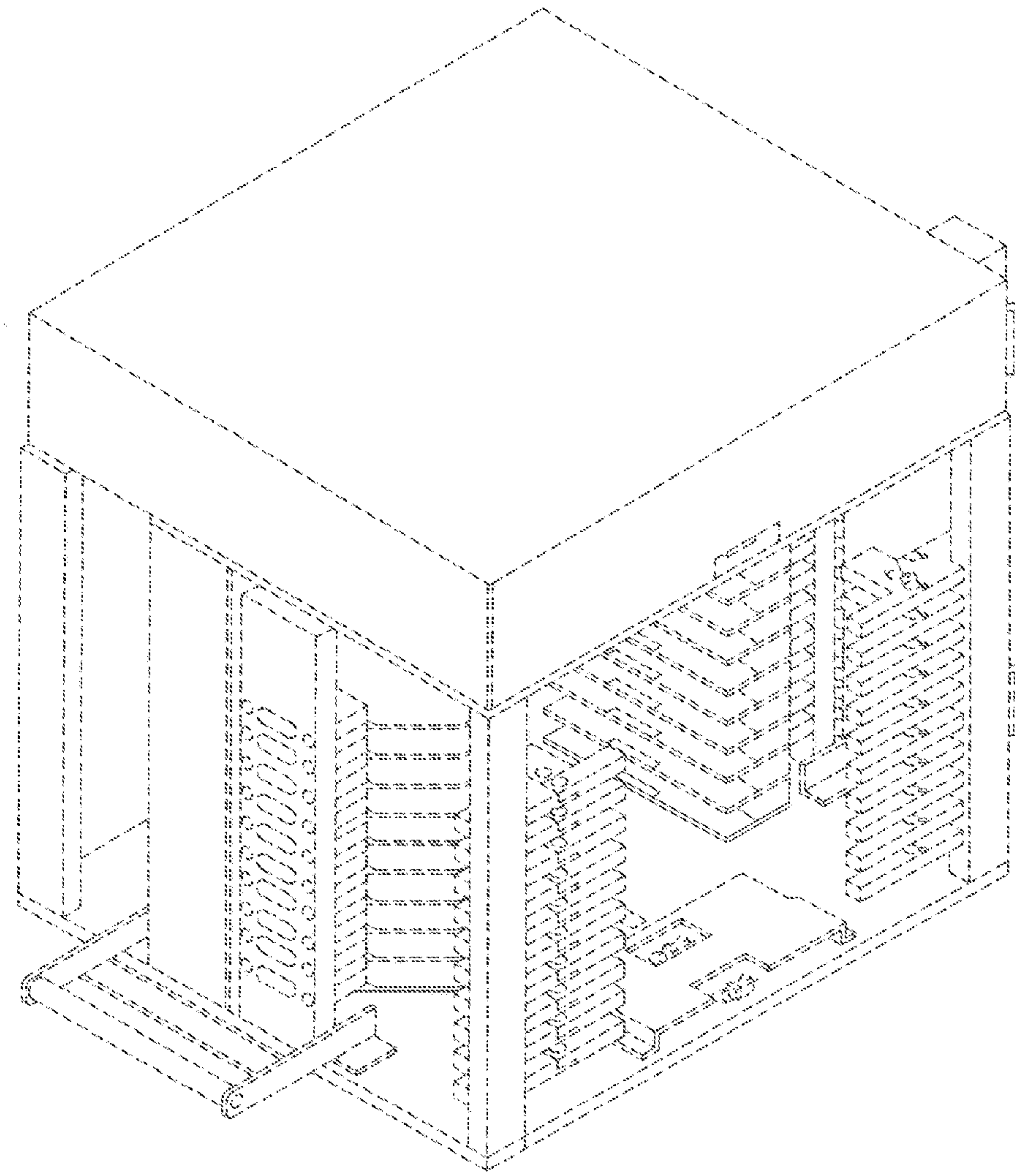


Fig. 6